

Special Issue

Heterogeneous Integration Electronic Devices

Message from the Guest Editors

This Special Issue aims to explore various aspects of heterogeneous integration, including materials, design, fabrication techniques, and applications, and will showcase the recent trends and challenges in this exciting field, providing a platform for researchers to exchange ideas, collaborate, and push the boundaries of what is possible in the realm of electronics integration. In this Special Issue, original research articles and reviews are welcome. Research areas may include (but are not limited to) the following:

- Materials for Heterogeneous Integration;
- Thermal Management for Heterogeneous Integrated Electronic Devices;
- Design and Modeling of Heterogeneous Integrated Devices;
- Fabrication Techniques for Heterogeneous Integration;
- Characterization and Testing of Heterogeneous Integrated Devices;
- Applications of Heterogeneous Integrated Devices;
- Integration and Interconnect Technologies;
- Challenges and Solutions in Heterogeneous Integration;
- Reliability and Lifetime Assessment.

Guest Editors

Prof. Dr. Bahgat G Sammakia

Department of Mechanical Engineering, Binghamton University,
Binghamton, NY 13902, USA

Prof. Dr. Srikanth Rangarajan

Department of Mechanical Engineering, Binghamton University,
Binghamton, NY 13902, USA

Deadline for manuscript submissions

closed (15 June 2024)



Electronics

an Open Access Journal
by MDPI

Impact Factor 2.6
CiteScore 6.1



mdpi.com/si/187394

Electronics
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
electronics@mdpi.com

[mdpi.com/journal/
electronics](https://mdpi.com/journal/electronics)





Electronics

an Open Access Journal
by MDPI

Impact Factor 2.6
CiteScore 6.1



[mdpi.com/journal/
electronics](https://mdpi.com/journal/electronics)



About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guestedited by leading experts in selected topics of interest.

Editor-in-Chief

Prof. Dr. Flavio Canavero

Department of Electronics and Telecommunications, Politecnico di Torino, 10129 Torino, Italy

Author Benefits

High Visibility:

indexed within Scopus, SCIE (Web of Science), CAPlus / SciFinder, Inspec, Ei Compendex and other databases.

Journal Rank:

JCR - Q2 (Engineering, Electrical and Electronic) /
CiteScore - Q1 (Electrical and Electronic Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 16.4 days after submission; acceptance to publication is undertaken in 2.6 days (median values for papers published in this journal in the second half of 2025).